ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INFORMATION AND ADDRESS	annockburn, Illinois, A	Il rights reserved un ntions.	ider both	his docume vel parts, tl	ent is a declaration he declaration er	on of the substand acompasses all lo	ces within the manufactur wer level materials for w	er listed iter hich the man	n. Note: if nufacturer l	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Tx			<ul> <li>Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and</li> </ul>				als and Mfg	and Mfg Information			
Supplier Information												
ompany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi	emi								2023-06-08			
Contact Name	Title - Contact			]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards	o Compliance		NA			Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site	W	eight*	UOM	Unit Type	
Π	NCV70501DW002G	V70501DW002G BIPOLAR STEPPE		I	2023-06-08		PHG	16	6.31	mg	Each	
Manufacturing Proccess Information					•	•	·					
Terminal Plating / Grid Array Material	terial Terminal Base Alloy		STD-020 MSL R	Rating	Peak Process Body Temperature Max T		ature Max Time at Peak	Temperature Number of Reflow Cycles		les		
Matte Tin (Sn) - annealed CU Alloy 2				260	С	30	seconds	3				
Comments												
ATTENTION: MSL 2 Rated item requires Dry	Pack (after electrical	test)										
or more information regarding material comp	position please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).								
Homogeneous Material	eneous Material Weight Unit of Measure Level		Substance	CAS	Exempt	Weight	Unit of Measure	
Die	8.95	mg	Supplier	Silicon (Si)	7440-21-3		8.95	mg
Die Attach	2.43	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.5589	mg
			Supplier	Silver (Ag)	7440-22-4		1.8711	mg
Lead Frame	58.58	mg	Supplier	Zinc (Zn)	7440-66-6		0.0586	mg
			Supplier	Iron (Fe)	7439-89-6		1.3473	mg
			Supplier	Copper (Cu)	7440-50-8		57.1155	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0586	mg
Mold Compound-Black	93.89	mg		Epoxy Phenol Resin	proprietary data		9.8584	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		84.0315	mg
Plating	1.91	mg	Supplier	Tin (Sn)	7440-31-5		1.91	mg
Wire Bond - Au	0.55	mg	Supplier	Gold (Au)	7440-57-5		0.55	mg